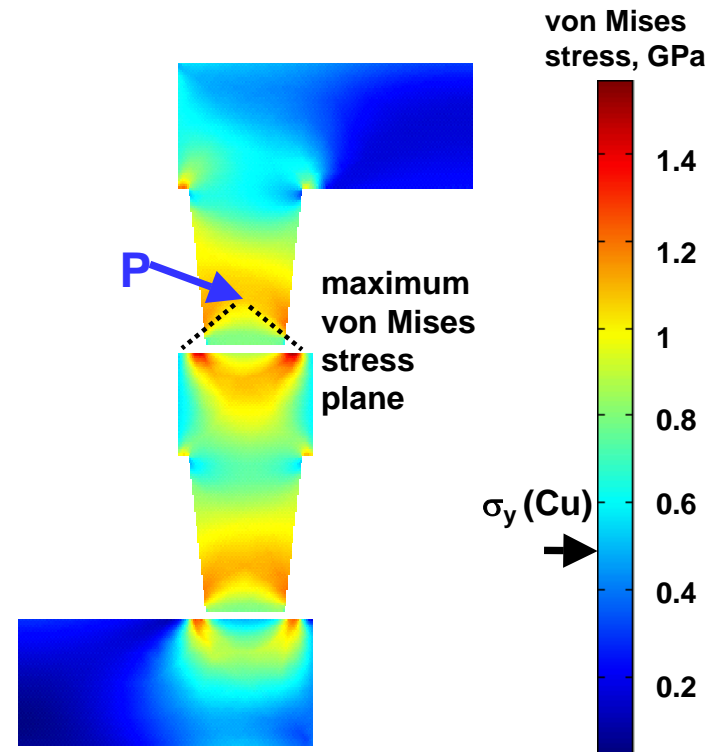
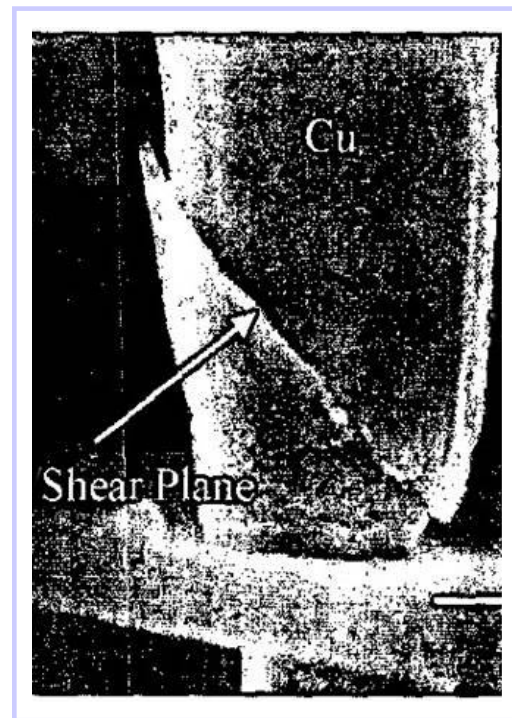
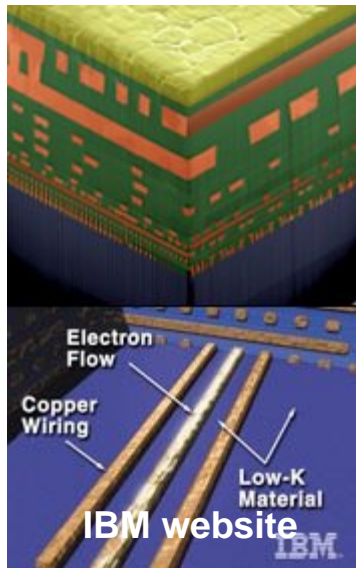


# Thermomechanical Stresses in 3D IC Inter-wafer Interconnects

Stacked via chains: prediction of failure



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SEM image (Filippi *et al.*)  
of a failed via embedded  
in SiLK.